

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Viasystems Group Inc.

Atty. Dkt. No.: 8245.016

Serial No.: 09/786,787

Examiner: Albert W. Paladini

Filed: May 10, 2001

Group Art Unit: 2827

For: NON-CIRCULAR  
MICRO VIA

BOX FEE AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following is being submitted in response to the Office Action dated October 23, 2002. Please amend the above-referenced patent application as follows:

Listing of Claims:

1. (Amended Herein) A wiring connection structure for a printed circuit board for interconnecting wiring circuit traces on a plurality of circuit trace layers applied on a plurality of printed circuit board layers and electrically isolated there between by the printed circuit board layers and having a printed circuit